

11017 U.S. PTO
10/085869



02/28/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APP. NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10085869	02/28/2002	257	67	2814	P. C. J.

****APPLICANTS:** Lo Wai Yew; Aripin Azhar Bin; Tiu Kong Bee;

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

SC11867MP

TITLE : Stacked die semiconductor device

U.S. DEPT. OF COMM./PAT. & TM.-PTO-4351 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Application Examiner	
PREPARED FOR ISSUE		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)